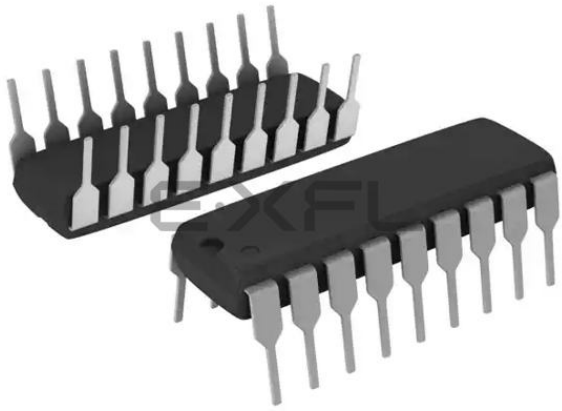

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	68 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c711-20e-p

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture in which program and data are fetched from the same memory using the same bus. Separating program and data buses further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions (35) execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The table below lists program memory (EPROM) and data memory (RAM) for each PIC16C71X device.

Device	Program Memory	Data Memory
PIC16C710	512 x 14	36 x 8
PIC16C71	1K x 14	36 x 8
PIC16C711	1K x 14	68 x 8
PIC16C715	2K x 14	128 x 8

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers, including the program counter, are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of ‘special optimal situations’ make programming with the PIC16CXX simple yet efficient. In addition, the learning curve is reduced significantly.

PIC16CXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between the data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a $\overline{\text{borrow}}$ bit and a $\overline{\text{digit}}$ $\overline{\text{borrow}}$ out bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

4.2 Data Memory Organization

The data memory is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bit RP0 is the bank select bit.

RP0 (STATUS<5>) = 1 → Bank 1

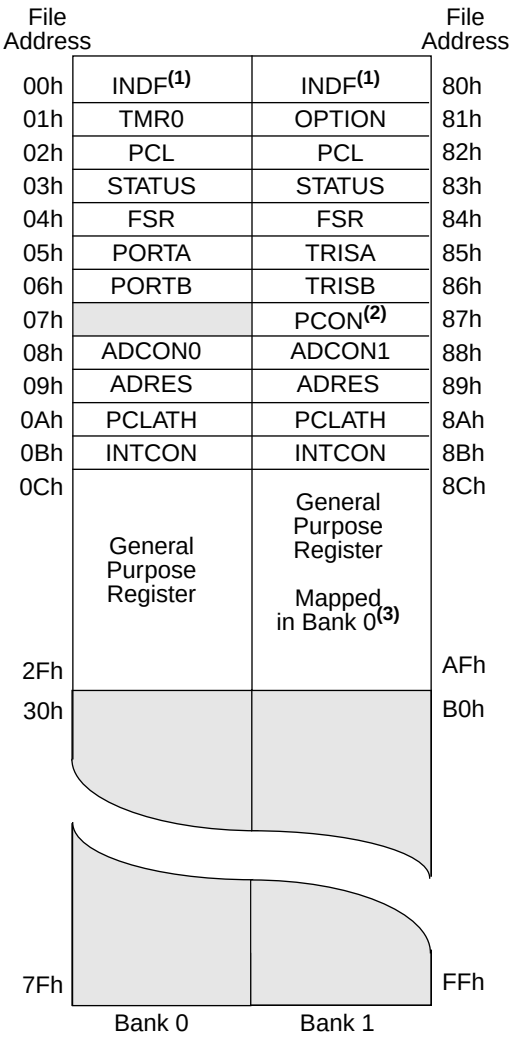
RP0 (STATUS<5>) = 0 → Bank 0

Each Bank extends up to 7Fh (128 bytes). The lower locations of each Bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers implemented as static RAM. Both Bank 0 and Bank 1 contain special function registers. Some "high use" special function registers from Bank 0 are mirrored in Bank 1 for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

FIGURE 4-4: PIC16C710/71 REGISTER FILE MAP



Unimplemented data memory locations, read as '0'.

Note 1: Not a physical register.

2: The PCON register is not implemented on the PIC16C71.

3: These locations are unimplemented in Bank 1. Any access to these locations will access the corresponding Bank 0 register.

4.2.2.1 STATUS REGISTER

Applicable Devices	710	71	711	715

The STATUS register, shown in Figure 4-7, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper-three bits and set the Z bit. This leaves the STATUS register as 000u u1uu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF, SWAPF and MOVWF instructions are used to alter the STATUS register because these instructions do not affect the Z, C or DC bits from the STATUS register. For other instructions, not affecting any status bits, see the "Instruction Set Summary."

Note 1: For those devices that do not use bits IRP and RP1 (STATUS<7:6>), maintain these bits clear to ensure upward compatibility with future products.

Note 2: The C and DC bits operate as a $\overline{borrow}$ and $\overline{digit\ borrow}$ bit, respectively, in subtraction. See the SUBLW and SUBWF instructions for examples.

FIGURE 4-7: STATUS REGISTER (ADDRESS 03h, 83h)

R/W-0	R/W-0	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **IRP:** Register Bank Select bit (used for indirect addressing)
1 = Bank 2, 3 (100h - 1FFh)
0 = Bank 0, 1 (00h - FFh)

bit 6-5: **RP1:RP0:** Register Bank Select bits (used for direct addressing)
11 = Bank 3 (180h - 1FFh)
10 = Bank 2 (100h - 17Fh)
01 = Bank 1 (80h - FFh)
00 = Bank 0 (00h - 7Fh)
Each bank is 128 bytes

bit 4: **$\overline{TO}$:** Time-out bit
1 = After power-up, CLRWDT instruction, or SLEEP instruction
0 = A WDT time-out occurred

bit 3: **$\overline{PD}$:** Power-down bit
1 = After power-up or by the CLRWDT instruction
0 = By execution of the SLEEP instruction

bit 2: **Z:** Zero bit
1 = The result of an arithmetic or logic operation is zero
0 = The result of an arithmetic or logic operation is not zero

bit 1: **DC:** Digit carry/$\overline{borrow}$ bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)(for $\overline{borrow}$ the polarity is reversed)
1 = A carry-out from the 4th low order bit of the result occurred
0 = No carry-out from the 4th low order bit of the result

bit 0: **C:** Carry/$\overline{borrow}$ bit (ADDWF, ADDLW, SUBLW, SUBWF instructions)
1 = A carry-out from the most significant bit of the result occurred
0 = No carry-out from the most significant bit of the result occurred
Note: For $\overline{borrow}$ the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (RRF, RLF) instructions, this bit is loaded with either the high or low order bit of the source register.

4.2.2.4 PIE1 REGISTER

Applicable Devices	710	71	711	715

This register contains the individual enable bits for the Peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 4-10: PIE1 REGISTER (ADDRESS 8Ch)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	ADIE	—	—	—	—	—	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **ADIE:** A/D Converter Interrupt Enable bit
1 = Enables the A/D interrupt
0 = Disables the A/D interrupt

bit 5-0: **Unimplemented:** Read as '0'

4.2.2.5 PIR1 REGISTER

Applicable Devices	710	71	711	715

This register contains the individual flag bits for the Peripheral interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 4-11: PIR1 REGISTER (ADDRESS 0Ch)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	ADIF	—	—	—	—	—	—
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
- n = Value at POR reset

bit 7: **Unimplemented:** Read as '0'

bit 6: **ADIF:** A/D Converter Interrupt Flag bit
1 = An A/D conversion completed
0 = The A/D conversion is not complete

bit 5-0: **Unimplemented:** Read as '0'

7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current). **The maximum recommended impedance for analog sources is 10 kΩ.** After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

EQUATION 7-1: A/D MINIMUM CHARGING TIME

$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \cdot (1 - e^{(-T_{CAP}/C_{HOLD}(R_{IC} + R_{SS} + R_S))})$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$T_{CAP} = -(51.2\ pF)(1\ k\Omega + R_{SS} + R_S) \ln(1/511)$

Example 7-1 shows the calculation of the minimum required acquisition time TACQ. This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

Rs = 10 kΩ

1/2 LSb error

VDD = 5V → Rss = 7 kΩ

Temp (application system max.) = 50°C

VHOLD = 0 @ t = 0

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

Note 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

Note 3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

Note 4: After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED AQUISITION TIME

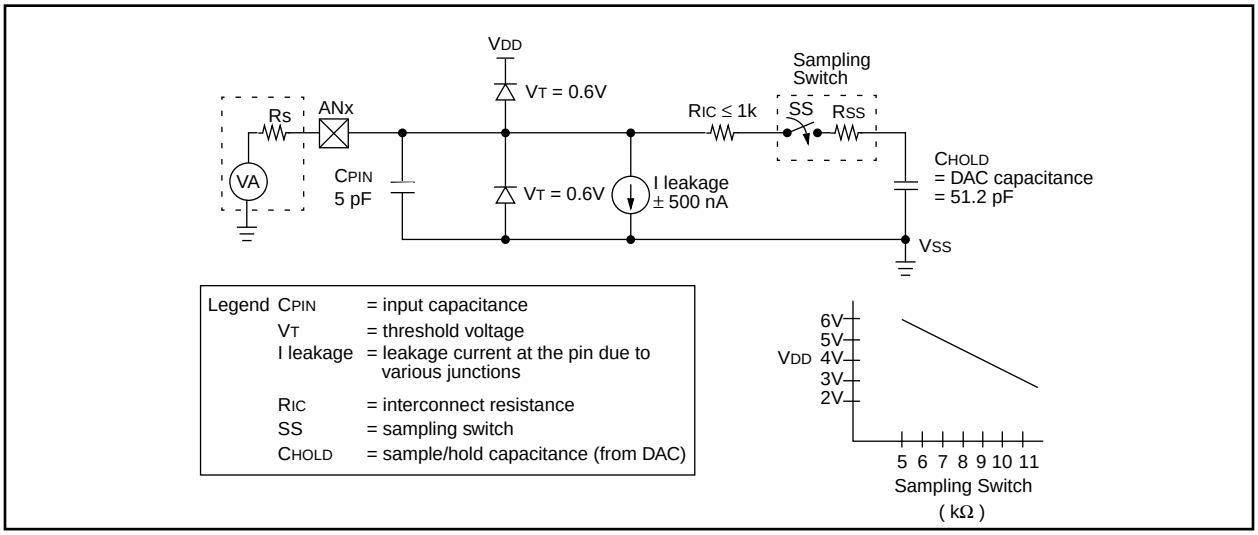
TACQ = Amplifier Settling Time +
Holding Capacitor Charging Time +
Temperature Coefficient

TACQ = 5 µs + TCAP + [(Temp - 25°C)(0.05 µs/°C)]

TCAP = -CHOLD (RIC + RSS + RS) ln(1/511)
-51.2 pF (1 kΩ + 7 kΩ + 10 kΩ) ln(0.0020)
-51.2 pF (18 kΩ) ln(0.0020)
-0.921 µs (-6.2364)
5.747 µs

TACQ = 5 µs + 5.747 µs + [(50°C - 25°C)(0.05 µs/°C)]
10.747 µs + 1.25 µs
11.997 µs

FIGURE 7-5: ANALOG INPUT MODEL



9.0 INSTRUCTION SET SUMMARY

Each PIC16CXX instruction is a 14-bit word divided into an OPCODE which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16CXX instruction set summary in Table 9-2 lists **byte-oriented**, **bit-oriented**, and **literal and control** operations. Table 9-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator specifies which file register is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is zero, the result is placed in the W register. If 'd' is one, the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an eight or eleven bit constant or literal value.

TABLE 9-1: OPCODE FIELD DESCRIPTIONS

Field	Description
f	Register file address (0x00 to 0x7F)
W	Working register (accumulator)
b	Bit address within an 8-bit file register
k	Literal field, constant data or label
x	Don't care location (= 0 or 1) The assembler will generate code with x = 0. It is the recommended form of use for compatibility with all Microchip software tools.
d	Destination select; d = 0: store result in W, d = 1: store result in file register f. Default is d = 1
label	Label name
TOS	Top of Stack
PC	Program Counter
PCLATH	Program Counter High Latch
GIE	Global Interrupt Enable bit
WDT	Watchdog Timer/Counter
$\overline{TO}$	Time-out bit
$\overline{PD}$	Power-down bit
dest	Destination either the W register or the specified register file location
[ ]	Options
( )	Contents
→	Assigned to
< >	Register bit field
∈	In the set of
italics	User defined term (font is courier)

The instruction set is highly orthogonal and is grouped into three basic categories:

- **Byte-oriented** operations
- **Bit-oriented** operations
- **Literal and control** operations

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles with the second cycle executed as a NOP. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1 μs. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2 μs.

Table 9-2 lists the instructions recognized by the MPASM assembler.

Figure 9-1 shows the general formats that the instructions can have.

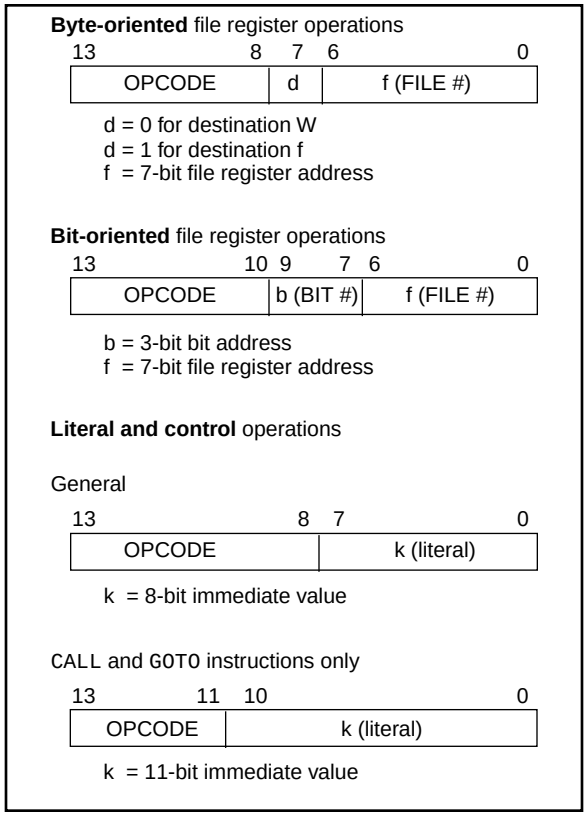
Note: To maintain upward compatibility with future PIC16CXX products, do not use the OPTION and TRIS instructions.

All examples use the following format to represent a hexadecimal number:

0xhh

where h signifies a hexadecimal digit.

FIGURE 9-1: GENERAL FORMAT FOR INSTRUCTIONS



XORLW **Exclusive OR Literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example:

```
XORLW   0xAF
```

Before Instruction

W = 0xB5

After Instruction

W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

00	0110	dfff	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to dest

Example

```
XORWF   REG  1
```

Before Instruction

REG = 0xAF
W = 0xB5

After Instruction

REG = 0x1A
W = 0xB5

Applicable Devices	710	71	711	715

11.3 DC Characteristics: PIC16C710-04 (Commercial, Industrial, Extended)
PIC16C711-04 (Commercial, Industrial, Extended)
PIC16C710-10 (Commercial, Industrial, Extended)
PIC16C711-10 (Commercial, Industrial, Extended)
PIC16C710-20 (Commercial, Industrial, Extended)
PIC16C711-20 (Commercial, Industrial, Extended)
PIC16LC710-04 (Commercial, Industrial, Extended)
PIC16LC711-04 (Commercial, Industrial, Extended)

DC CHARACTERISTICS							**Standard Operating Conditions (unless otherwise stated)** Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended) Operating voltage VDD range as described in DC spec Section 11.1 and Section 11.2.
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15VDD	V	For entire VDD range
D030A			VSS	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D031	with Schmitt Trigger buffer		VSS	-	0.2VDD	V	
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD	V	For entire VDD range
D041	with Schmitt Trigger buffer		0.8VDD	-	VDD	V	For entire VDD range
D042	$\overline{MCLR}$, RB0/INT		0.8VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C7X be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices	710	71	711	715

FIGURE 12-14: TYPICAL IDD vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

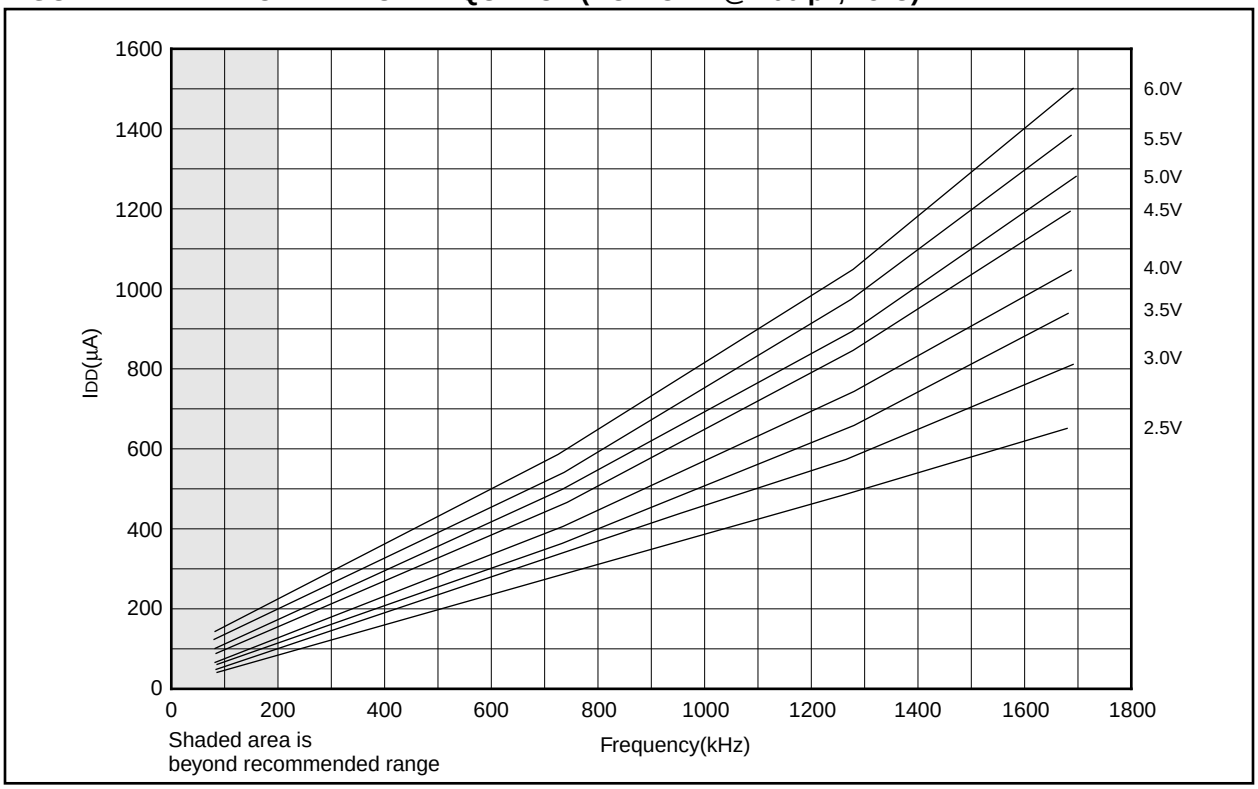
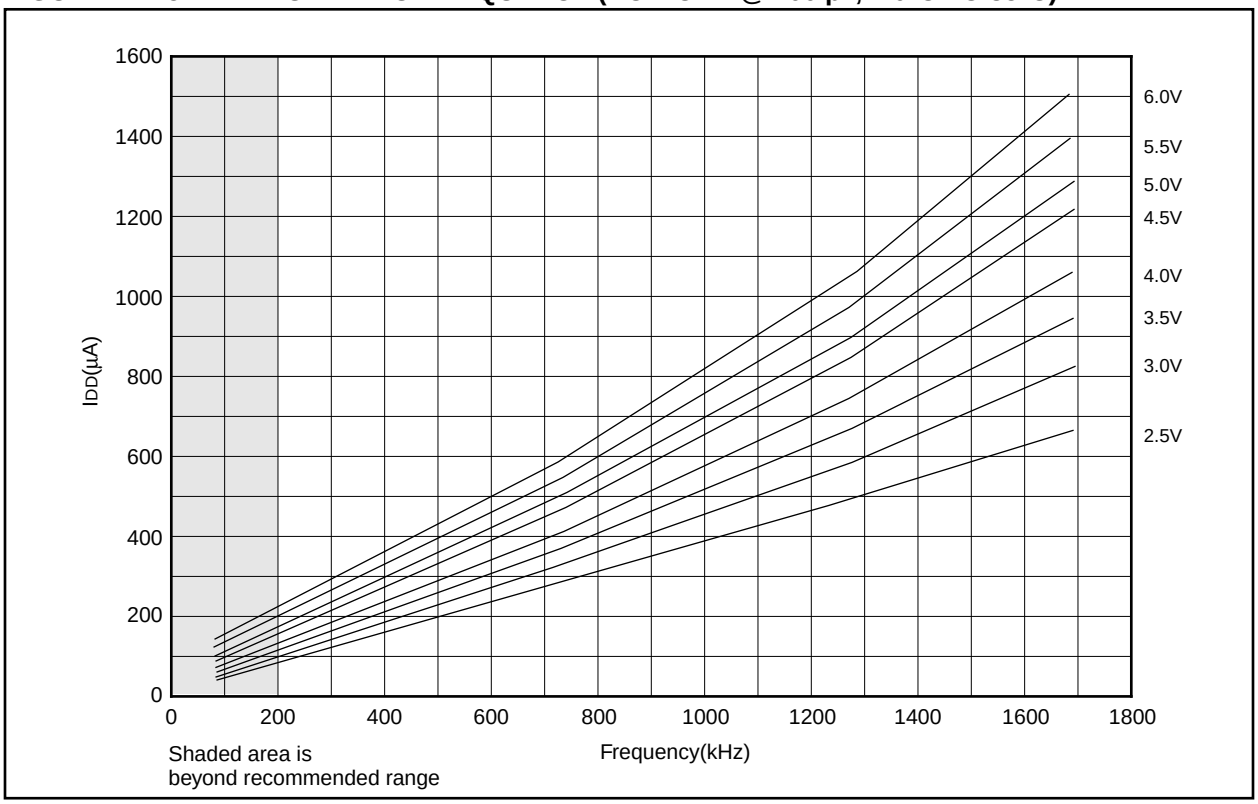


FIGURE 12-15: MAXIMUM IDD vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



Applicable Devices	710	71	711	715

FIGURE 12-22: TYPICAL XTAL STARTUP TIME vs. VDD (LP MODE, 25°C)

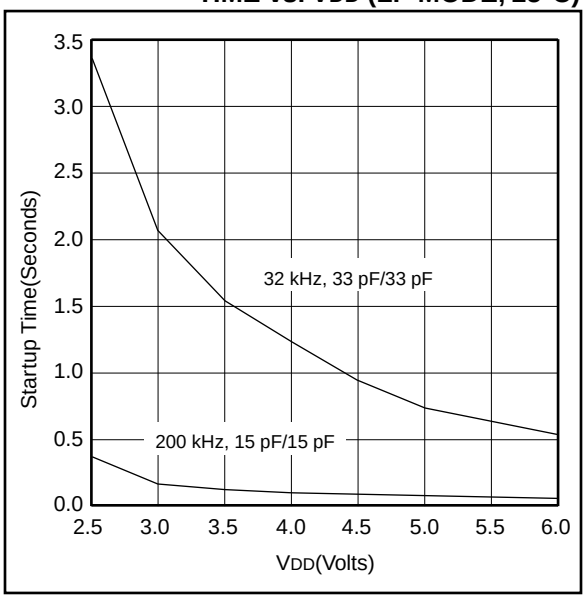


FIGURE 12-23: TYPICAL XTAL STARTUP TIME vs. VDD (HS MODE, 25°C)

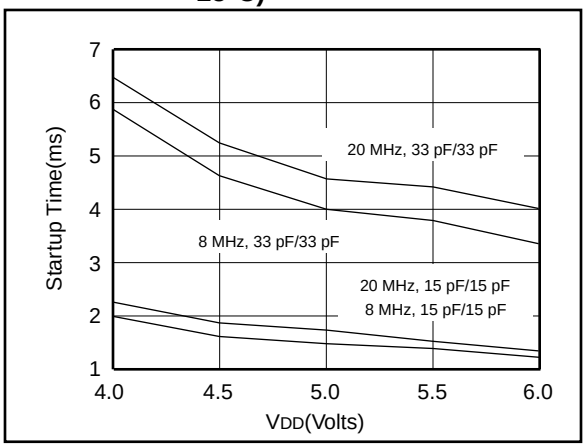


FIGURE 12-24: TYPICAL XTAL STARTUP TIME vs. VDD (XT MODE, 25°C)

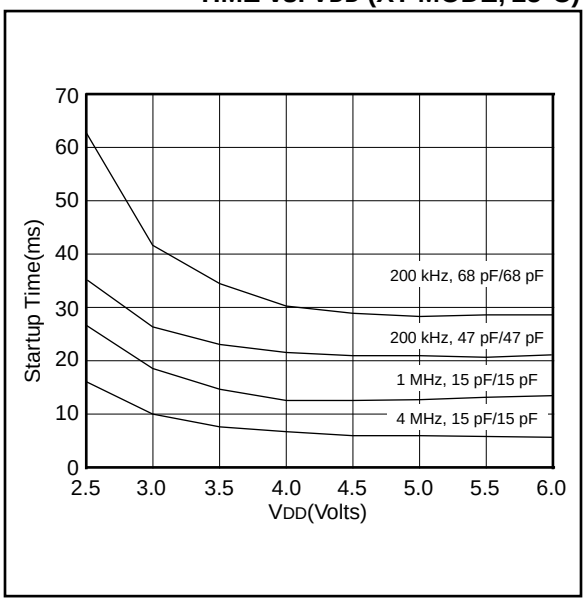


TABLE 12-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
32 kHz	Epson C-001R32.768K-A		± 20 PPM
200 kHz	STD XTL 200.000KHz		± 20 PPM
1 MHz	ECS ECS-10-13-1		± 50 PPM
4 MHz	ECS ECS-40-20-1		± 50 PPM
8 MHz	EPSON CA-301 8.000M-C		± 30 PPM
20 MHz	EPSON CA-301 20.000M-C		± 30 PPM

Applicable Devices	710	71	711	715

13.1 DC Characteristics: PIC16C715-04 (Commercial, Industrial, Extended) PIC16C715-10 (Commercial, Industrial, Extended) PIC16C715-20 (Commercial, Industrial, Extended))

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) -40°C ≤ TA ≤ +125°C (extended)				
Param. No.	**Characteristic**	**Sym**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	Supply Voltage	VDD	4.0	-	5.5	V	XT, RC and LP osc configuration
D001A			4.5	-	5.5	V	HS osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	Device in SLEEP mode
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2)	IDD	-	2.7	5	mA	XT, RC osc configuration (PIC16C715-04) FOSC = 4 MHz, VDD = 5.5V (Note 4)
D013			-	13.5	30	mA	HS osc configuration (PIC16C715-20) FOSC = 20 MHz, VDD = 5.5V
D015	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	µA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3)	IPD	-	10.5	42	µA	VDD = 4.0V, WDT enabled, -40°C to +85°C
D021			-	1.5	21	µA	VDD = 4.0V, WDT disabled, -0°C to +70°C
D021A			-	1.5	24	µA	VDD = 4.0V, WDT disabled, -40°C to +85°C
D021B			-	1.5	30	µA	VDD = 4.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	µA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

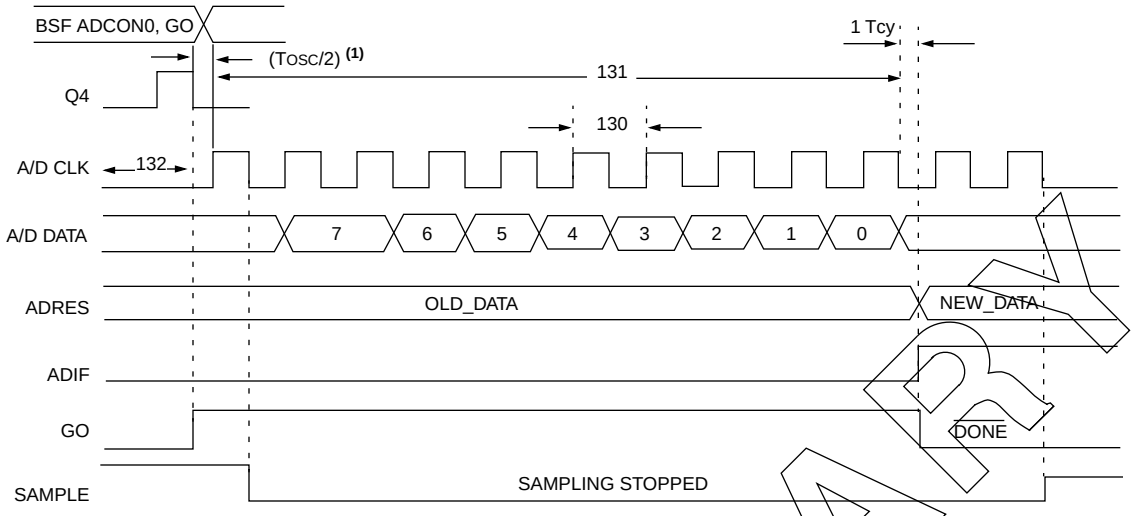
3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

Applicable Devices	710	71	711	715

FIGURE 13-7: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 13-8: A/D CONVERSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	1.6		—	µs	VREF ≥ 3.0V
			2.0		—	µs	VREF full range
130	TAD	A/D Internal RC Oscillator source					ADCS1:ADCS0 = 11 (RC oscillator source)
			3.0	6.0	9.0	µs	PIC16LC715, VDD = 3.0V
			2.0	4.0	6.0	µs	PIC16C715
131	TCNV	Conversion time (not including S/H time). Note 1	—	9.5TAD	—	—	
132	TACQ	Acquisition time	Note 2	20	—	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following TCY cycle.

Applicable Devices	710	71	711	715

FIGURE 14-29: TYPICAL IDD vs. FREQUENCY (HS MODE, 25°C)

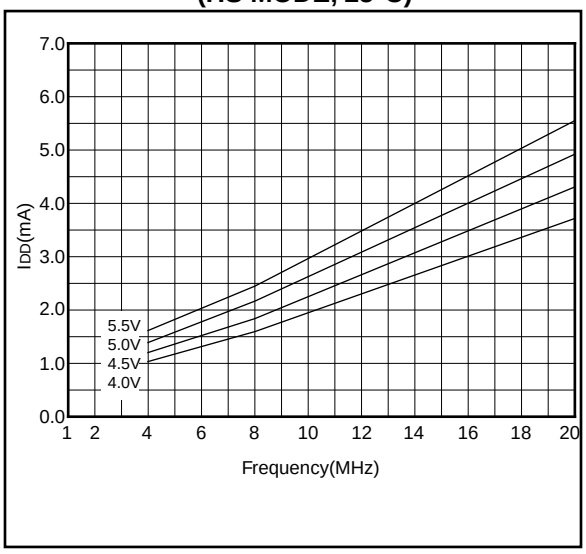
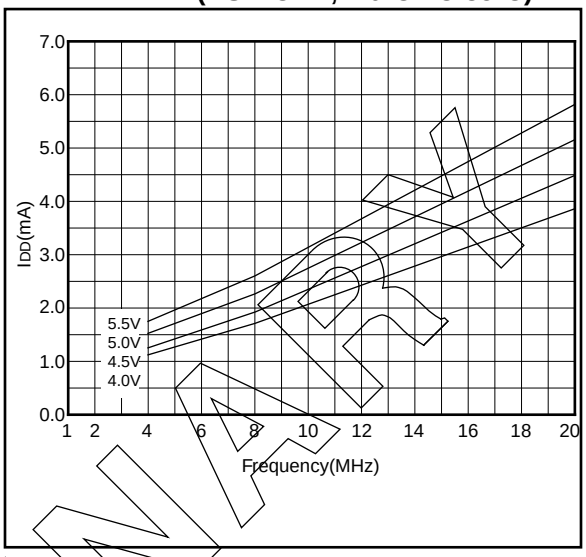


FIGURE 14-30: MAXIMUM IDD vs. FREQUENCY (HS MODE, -40°C TO 85°C)



Applicable Devices	710	71	711	715

15.3 DC Characteristics: PIC16C71-04 (Commercial, Industrial)
PIC16C71-20 (Commercial, Industrial)
PIC16LC71-04 (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** OOperating temperature 0°C ≤ TA ≤ +70°C (commercial) -40°C ≤ TA ≤ +85°C (industrial) Operating voltage VDD range as described in DC spec Section 15.1 and Section 15.2.				
Param No.	**Characteristic**	**Sym**	**Min**	**Typ †**	**Max**	**Units**	**Conditions**
	Input Low Voltage						
	I/O ports	VIL					
D030	with TTL buffer		VSS	-	0.15V	V	For entire VDD range
D031	with Schmitt Trigger buffer		VSS	-	0.8V	V	4.5 ≤ VDD ≤ 5.5V
D032	$\overline{MCLR}$, OSC1 (in RC mode)		VSS	-	0.2VDD	V	
D033	OSC1 (in XT, HS and LP)		VSS	-	0.3VDD	V	Note1
	Input High Voltage						
	I/O ports (Note 4)	VIH		-			
D040	with TTL buffer		2.0	-	VDD	V	4.5 ≤ VDD ≤ 5.5V
D040A			0.25VDD + 0.8V	-	VDD		For entire VDD range
D041	with Schmitt Trigger buffer		0.85VDD	-	VDD		For entire VDD range
D042	$\overline{MCLR}$, RB0/INT		0.85VDD	-	VDD	V	
D042A	OSC1 (XT, HS and LP)		0.7VDD	-	VDD	V	Note1
D043	OSC1 (in RC mode)		0.9VDD	-	VDD	V	
D070	PORTB weak pull-up current	IPURB	50	250	†400	µA	VDD = 5V, VPIN = VSS
	Input Leakage Current (Notes 2, 3)						
D060	I/O ports	IIL	-	-	±1	µA	Vss ≤ VPIN ≤ VDD, Pin at hi-impedance
D061	$\overline{MCLR}$, RA4/T0CKI		-	-	±5	µA	Vss ≤ VPIN ≤ VDD
D063	OSC1		-	-	±5	µA	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
	Output Low Voltage						
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5mA, VDD = 4.5V, -40°C to +85°C
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6mA, VDD = 4.5V, -40°C to +85°C
	Output High Voltage						
D090	I/O ports (Note 3)	VOH	VDD - 0.7	-	-	V	IOH = -3.0mA, VDD = 4.5V, -40°C to +85°C
D092	OSC2/CLKOUT (RC osc config)		VDD - 0.7	-	-	V	IOH = -1.3mA, VDD = 4.5V, -40°C to +85°C
D130*	**Open-Drain High Voltage**	VOD	-	-	14	V	RA4 pin

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC16C71 be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: PIC16C71 Rev. "Ax" INT pin has a TTL input buffer. PIC16C71 Rev. "Bx" INT pin has a Schmitt Trigger input buffer.

Applicable Devices	710	71	711	715

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C71

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. **In some graphs or tables the data presented are outside specified operating range (e.g. outside specified VDD range). This is for information only and devices are guaranteed to operate properly only within the specified range.**

Note:	The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution while 'max' or 'min' represents (mean + 3σ) and (mean - 3σ) respectively where σ is standard deviation.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY VS. TEMPERATURE

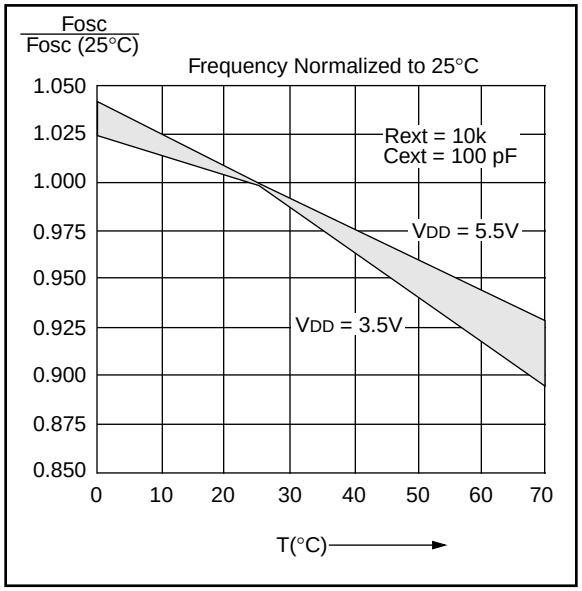


FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY VS. VDD

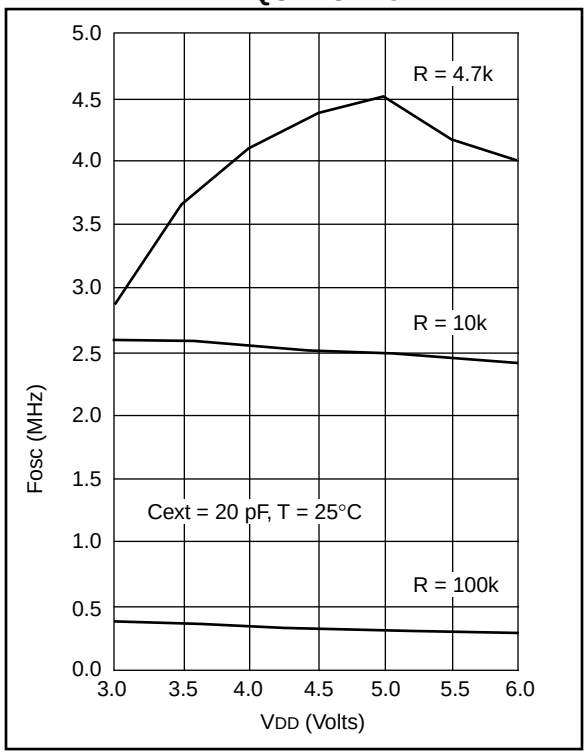
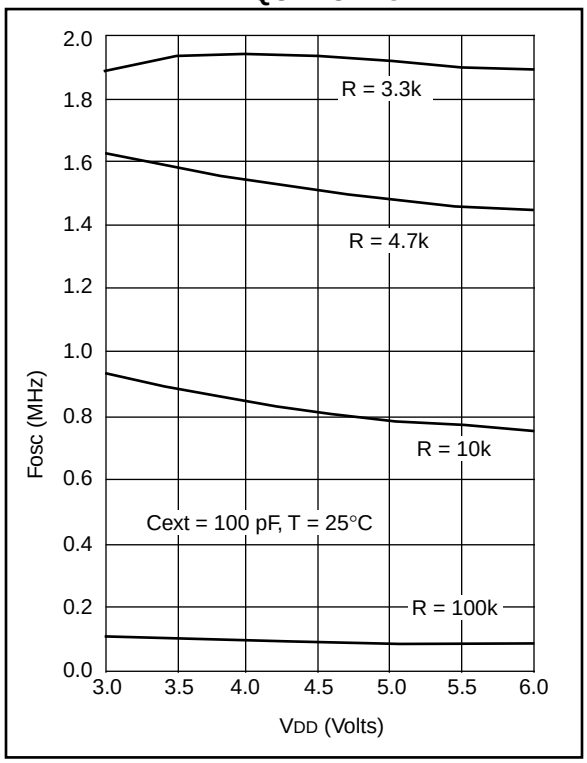


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY VS. VDD



APPENDIX C: WHAT'S NEW

1. Consolidated all pin compatible 18-pin A/D based devices into one data sheet.

APPENDIX D: WHAT'S CHANGED

1. Minor changes, spelling and grammatical changes.
2. Low voltage operation on the PIC16LC710/711/715 has been reduced from 3.0V to 2.5V.
3. Part numbers of the PIC16C70 and PIC16C71A have changed to PIC16C710 and PIC16C711, respectively.

LIST OF TABLES

ON-LINE SUPPORT

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Use Microchip's Bulletin Board Service (BBS) to get current information and help about Microchip products. Microchip provides the BBS communication channel for you to use in extending your technical staff with microcontroller and memory experts.

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The web site, like the BBS, is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

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The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

ftp://ftp.futureone.com/pub/microchip

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

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You can telnet or ftp to the Microchip BBS at the address: **mchipbbs.microchip.com**

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When using the BBS via the Compuserve Network, in most cases, a local call is your only expense. The Microchip BBS connection does not use CompuServe membership services, therefore you do not need CompuServe membership to join Microchip's BBS. There is no charge for connecting to the Microchip BBS.

The procedure to connect will vary slightly from country to country. Please check with your local CompuServe agent for details if you have a problem. CompuServe service allow multiple users various baud rates depending on the local point of access.

The following connect procedure applies in most locations.

1. Set your modem to 8-bit, No parity, and One stop (8N1). This is not the normal CompuServe setting which is 7E1.
2. Dial your local CompuServe access number.
3. Depress the **<Enter>** key and a garbage string will appear because CompuServe is expecting a 7E1 setting.
4. Type +, depress the **<Enter>** key and "`Host Name:`" will appear.
5. Type MCHIPBBS, depress the **<Enter>** key and you will be connected to the Microchip BBS.

In the United States, to find the CompuServe phone number closest to you, set your modem to 7E1 and dial (800) 848-4480 for 300-2400 baud or (800) 331-7166 for 9600-14400 baud connection. After the system responds with "`Host Name:`", type `NETWORK`, depress the **<Enter>** key and follow CompuServe's directions.

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